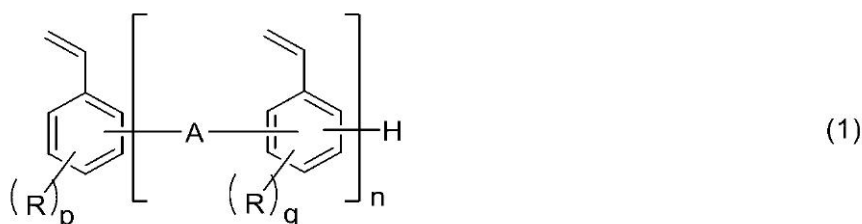


ABSTRACT

The present invention provides a curable resin composition having excellent storage stability and exhibiting a low dielectric loss tangent, and a cured product thereof. This curable resin composition contains a compound represented by formula (1) and a compound represented by formula (2). (In formula (1), A represents a hydrocarbon group having 1-20 carbon atoms, and each of a plurality of R's independently represents a hydrogen atom, a hydrocarbon group having 1-10 carbon atoms, or a halogenated alkyl group having 1-10 carbon atoms. p represents an integer of 0-4, q represents an integer of 0-3, and n represents an average value for number of repetitions, which is $1 \leq n \leq 20$.) (In formula (2), each of R1 and R2 independently represents a hydrocarbon group having 1-20 carbon atoms, and n represents an integer of 0-3.)

[Formula 1]



15 [Formula 2]



FIG. 2